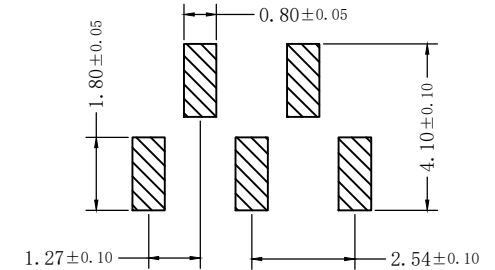
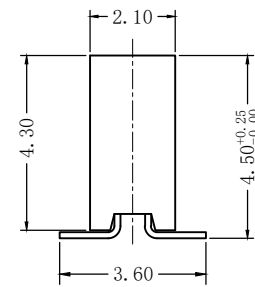
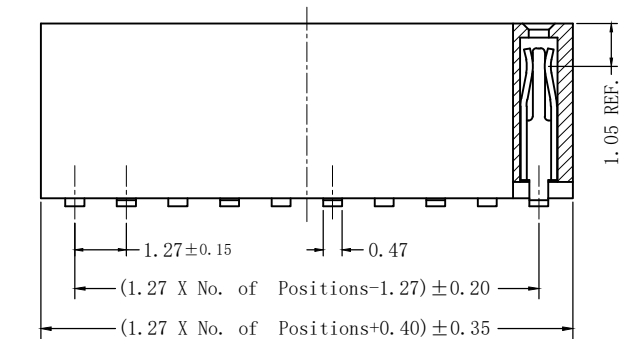
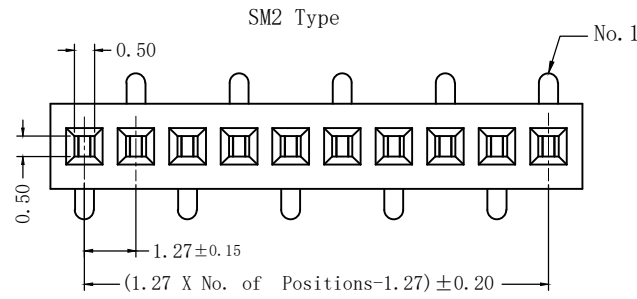
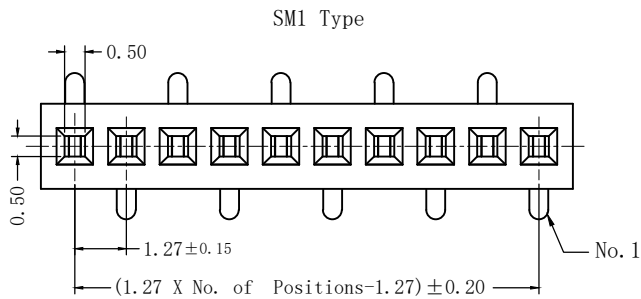
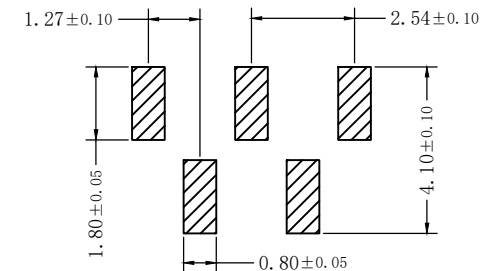


版次	变更内容	审核	日期



Recommended PCB Layout SM1 Type



Recommended PCB Layout SM2 Type

弯曲度: 1*02P ~ 1*20P 0.30 MAX.
 1*21P ~ 1*35P 0.40 MAX.
 1*36P ~ 1*50P 0.50 MAX.

203-1 XXX-3C-2*xxP G-A

贴板类型
 SM1: Pin 1 朝下
 SM2: Pin 1 朝上

单排芯数
 01~50P

塑高
 4.3: 4.30mm

电镀
 G: 镀金Gold Flash
 1G: 镀金1u"
 3G: 镀金3u"
 (镀金可订制)

技术参数: SPECIFICATIONS

额定电流 (Current Rating): 1A
 绝缘电阻 (Insulation Resistance): 1000MΩ Min.
 接触电阻 (Contact Resistance): 20m Ω Max.
 额定电压 (Dielectric Withstanding Voltage): AC 500V
 工作温度 (Operating Temperature): -40°C ~ +105°C
 最大加工温度 (Max Processing Temp): (230°C for 30~60 seconds)
 (260°C for 10 seconds)

接触材料 (Contact Material): 磷青铜(Phosphor Bronze), THICKNESS 0.15mm
 塑胶材料 (Insulator Material): 尼龙(Nylon)-9T, UL 94V-0, 颜色: 黑色
 接触电镀 (Contact Plating): 镀金 (Gold plated)
 (电镀规格可根据客户要求来定制)
 Opitonal planting on request.

公差:	版次:	A	上海宗进电子科技有限公司 Shanghai Zong Jin Electron Technology Co.LTD		
. X ±0.35	比例:		型号: 203-1SMx-3C-1*xxPG-A	签名	日期
. XX ±0.25	单位:	mm			
. XXX ±2°	页码:	1/3	描述: 1.27单排贴板排母	绘图:	
LNLB	图号:			确认:	
			审核:		